

# DATA SHEET

## **74LVC1GX04** X-tal driver

Product specification

2003 Aug 13

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**X-tal driver****74LVC1GX04**

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**FEATURES**

- Wide supply voltage range from 1.65 to 5.5 V
- 5 V tolerant input and a 5 V overvoltage tolerant powered down output.
- High noise immunity
- Complies with JEDEC standard:
  - JESD8-7 (1.65 to 1.95 V)
  - JESD8-5 (2.3 to 2.7 V)
  - JESD8B/JESD36 (2.7 to 3.6 V).
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- SOT363 and SOT457 package
- ESD protection:
  - HBM EIA/JESD22-A114-A exceeds 2000 V
  - MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from  $-40$  to  $+85$  °C and  $-40$  to  $+125$  °C.

**DESCRIPTION**

The 74LVC1GX04 is a high-performance, low-power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of this device as translator in a mixed 3.3 and 5 V environment.

This device is fully specified for partial power-down applications using  $I_{off}$  at output Y. The  $I_{off}$  circuitry disables the output Y, preventing the damaging backflow current through the device when it is powered down.

The 74LVC1GX04 combines the functions of the 74LVC1GU04 and 74LVC1G04 to provide a device optimized for use in crystal oscillator applications.

The integration of the two devices into the 74LVC1GX04 produces the benefits of a compact footprint, lower power dissipation and stable operation over a wide range of frequency and temperature.

## X-tal driver

## 74LVC1GX04

**QUICK REFERENCE DATA**GND = 0 V; T<sub>amb</sub> = 25 °C.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay input X1 to output X2	V <sub>CC</sub> = 1.8 V; C <sub>L</sub> = 30 pF; R <sub>L</sub> = 1 kΩ	2.1	ns
		V <sub>CC</sub> = 2.5 V; C <sub>L</sub> = 30 pF; R <sub>L</sub> = 500 Ω	1.7	ns
		V <sub>CC</sub> = 2.7 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	2.5	ns
		V <sub>CC</sub> = 3.3 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	2.1	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	1.6	ns
	propagation delay input X1 to output Y	V <sub>CC</sub> = 1.8 V; C <sub>L</sub> = 30 pF; R <sub>L</sub> = 1 kΩ	4.4	ns
		V <sub>CC</sub> = 2.5 V; C <sub>L</sub> = 30 pF; R <sub>L</sub> = 500 Ω	2.9	ns
		V <sub>CC</sub> = 2.7 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	3.0	ns
		V <sub>CC</sub> = 3.3 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	2.8	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 50 pF; R <sub>L</sub> = 500 Ω	2.3	ns
C <sub>I</sub>	input capacitance		5	pF
C <sub>PD</sub>	power dissipation capacitance per buffer	output enabled; notes 1 and 2	35	pF

**Notes**

1. C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;f<sub>o</sub> = output frequency in MHz;C<sub>L</sub> = output load capacitance in pF;V<sub>CC</sub> = supply voltage in Volts;

N = total load switching outputs;

∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

2. The condition is V<sub>I</sub> = GND to V<sub>CC</sub>.

**FUNCTION TABLE**

See note 1.

INPUT	OUTPUT	
X1	X2	Y
H	L	H
L	H	L

**Note**

1. H = HIGH voltage level;  
L = LOW voltage level.

## X-tal driver

## 74LVC1GX04

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE					
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING
74LVC1GX04GW	-40 to +125 °C	6	TSSOP6	plastic	SOT363	VX
74LVC1GX04GV	-40 to +125 °C	6	TSSOP6	plastic	SOT457	VX4

## PINNING

PIN	SYMBOL	DESCRIPTION
1	n.c.	not connected
2	GND	ground (0 V)
3	X1	data input
4	X2	data output
5	V <sub>CC</sub>	supply voltage
6	Y	data output

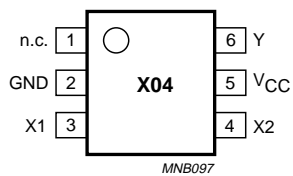


Fig.1 Pin configuration.

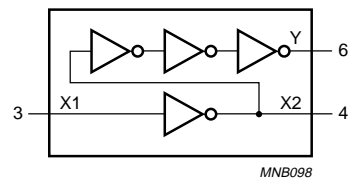


Fig.2 Logic symbol.

## X-tal driver

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## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage	note 1	1.65	5.5	V
$V_I$	input voltage		0	5.5	V
$V_O$	output voltage	note 2			
		active mode	0	$V_{CC}$	V
		Power-down mode; $V_{CC} = 0$ V	0	5.5	V
$T_{amb}$	operating ambient temperature		-40	+125	°C
$t_r, t_f$	input rise and fall times	$V_{CC} = 1.65$ to $2.7$ V	0	20	ns/V
		$V_{CC} = 2.7$ to $5.5$ V	0	10	ns/V

## Notes

- For use of a regular crystal oscillator, the recommended minimum  $V_{CC}$  should be 2.0 V.
- Only for output Y.

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input diode current	$V_I < 0$	-	-50	mA
$V_I$	input voltage	note 1	-0.5	+6.5	V
$I_{OK}$	output diode current	$V_O > V_{CC}$ or $V_O < 0$	-	$\pm 50$	mA
$V_O$	output voltage	active mode; notes 1 and 2	-0.5	$V_{CC} + 0.5$	V
		Power-down mode; notes 1 and 2	-0.5	+6.5	V
$I_O$	output source or sink current	$V_O = 0$ to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}, I_{GND}$	$V_{CC}$ or GND current		-	$\pm 100$	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_D$	power dissipation	$T_{amb} = -40$ to $+125$ °C	-	300	mW

## Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

## X-tal driver

## 74LVC1GX04

**DC CHARACTERISTICS**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	$V_{CC\Omega}$ (V)				
$T_{amb} = -40$ to $+85$ °C; note 1							
$V_{IH}$	HIGH-level input voltage		1.65 to 5.5	$0.75 \times V_{CC}$	–	–	V
$V_{IL}$	LOW-level input voltage		1.65 to 5.5	–	–	$0.25 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	1.65 to 5.5	–	–	0.1	V
		$I_O = 100 \mu A$	1.65	–	–	0.45	V
		$I_O = 4$ mA	2.3	–	–	0.3	V
		$I_O = 8$ mA	2.7	–	–	0.4	V
		$I_O = 12$ mA	3.0	–	–	0.55	V
		$I_O = 24$ mA	4.5	–	–	0.55	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	1.65 to 5.5	$V_{CC} - 0.1$	–	–	V
		$I_O = -100 \mu A$	1.65	1.2	–	–	V
		$I_O = -4$ mA	2.3	1.9	–	–	V
		$I_O = -8$ mA	2.7	2.2	–	–	V
		$I_O = -12$ mA	3.0	2.3	–	–	V
		$I_O = -24$ mA	4.5	3.8	–	–	V
$I_{LI}$	input leakage current	$V_I = 5.5$ V or GND	5.5	–	$\pm 0.1$	$\pm 5$	$\mu A$
$I_{off}$	power OFF leakage current	$V_I$ or $V_O = 5.5$ V; note 2	0	–	$\pm 0.1$	$\pm 10$	$\mu A$
$I_{CC}$	quiescent supply current	$V_I = V_{CC}$ or GND; $I_O = 0$	5.5	–	0.1	10	$\mu A$

## X-tal driver

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SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	$V_{CC\Omega}$ (V)				
<b><math>T_{amb} = -40</math> to <math>+125</math> °C</b>							
$V_{IH}$	HIGH-level input voltage		1.65 to 5.5	$0.8 \times V_{CC}$	–	–	V
$V_{IL}$	LOW-level input voltage		1.65 to 5.5	–	–	$0.2 \times V_{CC}$	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	1.65 to 5.5	–	–	0.1	V
		$I_O = 100 \mu A$	1.65	–	–	0.70	V
		$I_O = 4 \text{ mA}$	2.3	–	–	0.45	V
		$I_O = 8 \text{ mA}$	2.7	–	–	0.60	V
		$I_O = 12 \text{ mA}$	3.0	–	–	0.80	V
		$I_O = 24 \text{ mA}$	4.5	–	–	0.80	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$	1.65 to 5.5	$V_{CC} - 0.1$	–	–	V
		$I_O = -100 \mu A$	1.65	0.95	–	–	V
		$I_O = -4 \text{ mA}$	2.3	1.7	–	–	V
		$I_O = -8 \text{ mA}$	2.7	1.9	–	–	V
		$I_O = -12 \text{ mA}$	3.0	2.0	–	–	V
		$I_O = -24 \text{ mA}$	4.5	3.4	–	–	V
$I_{LI}$	input leakage current	$V_I = 5.5 \text{ V}$ or GND	5.5	–	–	$\pm 20$	$\mu A$
$I_{off}$	power OFF leakage current	$V_I$ or $V_O = 5.5 \text{ V}$ ; note 2	0	–	–	$\pm 20$	$\mu A$
$I_{CC}$	quiescent supply current	$V_I = V_{CC}$ or GND; $I_O = 0$	5.5	–	–	40	$\mu A$

**Notes**

1. All typical values are measured at  $V_{CC} = 3.3 \text{ V}$  and  $T_{amb} = 25$  °C.
2.  $V_O$  only for output Y.

## X-tal driver

## 74LVC1GX04

## AC CHARACTERISTICS

GND = 0 V.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C; note 1</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay input X1 to output X2	see Figs 3 and 5	1.65 to 1.95	0.5	2.1	5.0	ns
			2.3 to 2.7	0.3	1.7	4.0	ns
			2.7	0.3	2.5	4.5	ns
			3.0 to 3.6	0.3	2.1	3.7	ns
			4.5 to 5.5	0.3	1.6	3.0	ns
	propagation delay input X1 to output Y	X2 no external load; see Figs 4 and 5	1.65 to 1.95	1.0	4.4	10.0	ns
			2.3 to 2.7	0.5	2.9	6.0	ns
			2.7	0.5	3.0	6.0	ns
			3.0 to 3.6	0.5	2.8	5.5	ns
			4.5 to 5.5	0.5	2.3	4.5	ns
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay input X1 to output X2	see Figs 3 and 5	1.65 to 1.95	0.5	–	6.5	ns
			2.3 to 2.7	0.3	–	5.0	ns
			2.7	0.3	–	5.6	ns
			3.0 to 3.6	0.3	–	4.5	ns
			4.5 to 5.5	0.3	–	3.8	ns
	propagation delay input X1 to output Y	X2 no external load; see Figs 4 and 5	1.65 to 1.95	1.0	–	12.5	ns
			2.3 to 2.7	0.5	–	7.5	ns
			2.7	0.5	–	7.5	ns
			3.0 to 3.6	0.5	–	6.9	ns
			4.5 to 5.5	0.5	–	5.6	ns

## Note

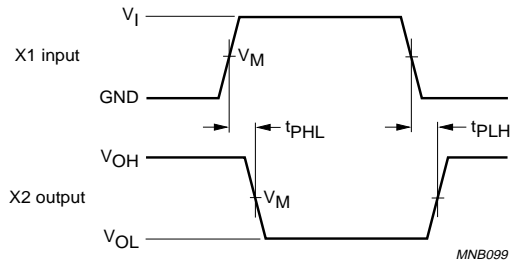
1. All typical values are measured at T<sub>amb</sub> = 25 °C.



X-tal driver

74LVC1GX04

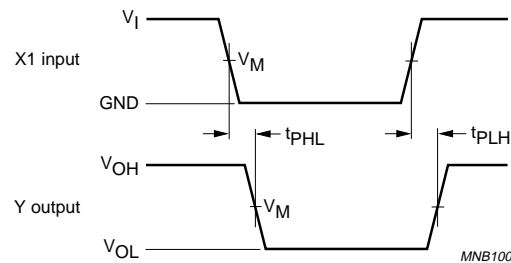
AC WAVEFORMS



V <sub>CC</sub>	V <sub>M</sub>	INPUT	
		V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>
1.65 to 1.95 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.0 ns
2.3 to 2.7 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.0 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns
4.5 to 5.5 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.5 ns

V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage drop that occur with the output load.

Fig.3 The input X1 to output X2 propagation delay.



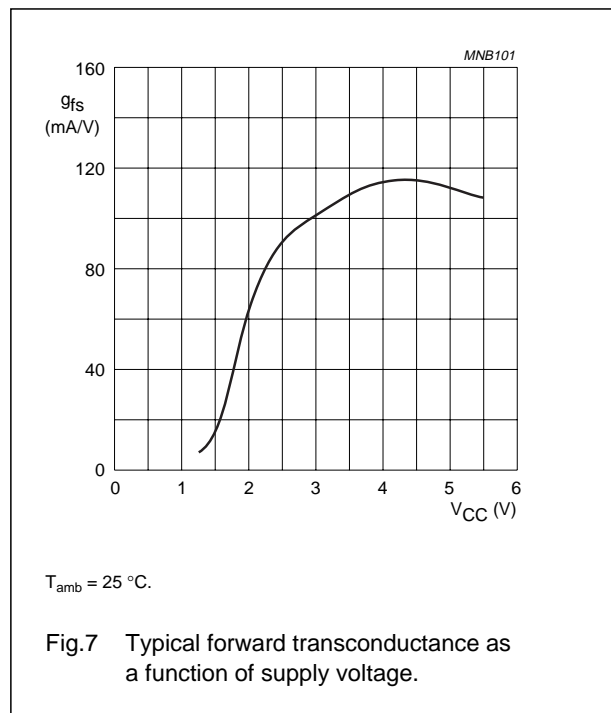
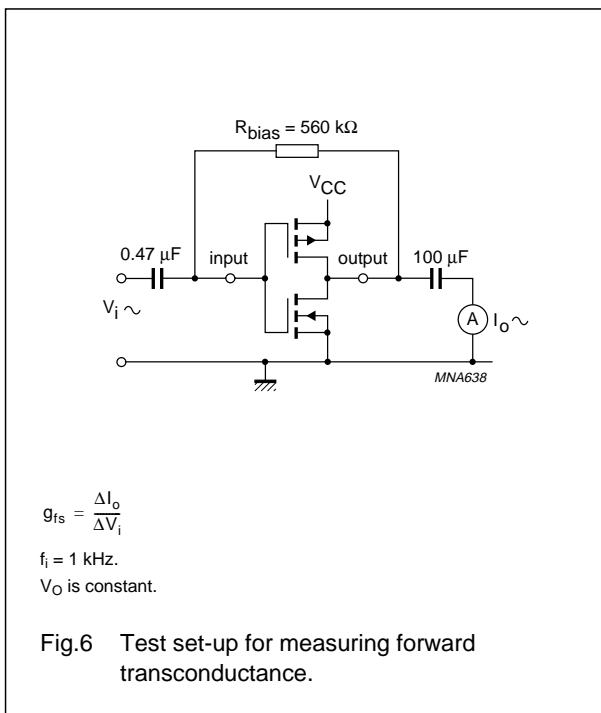
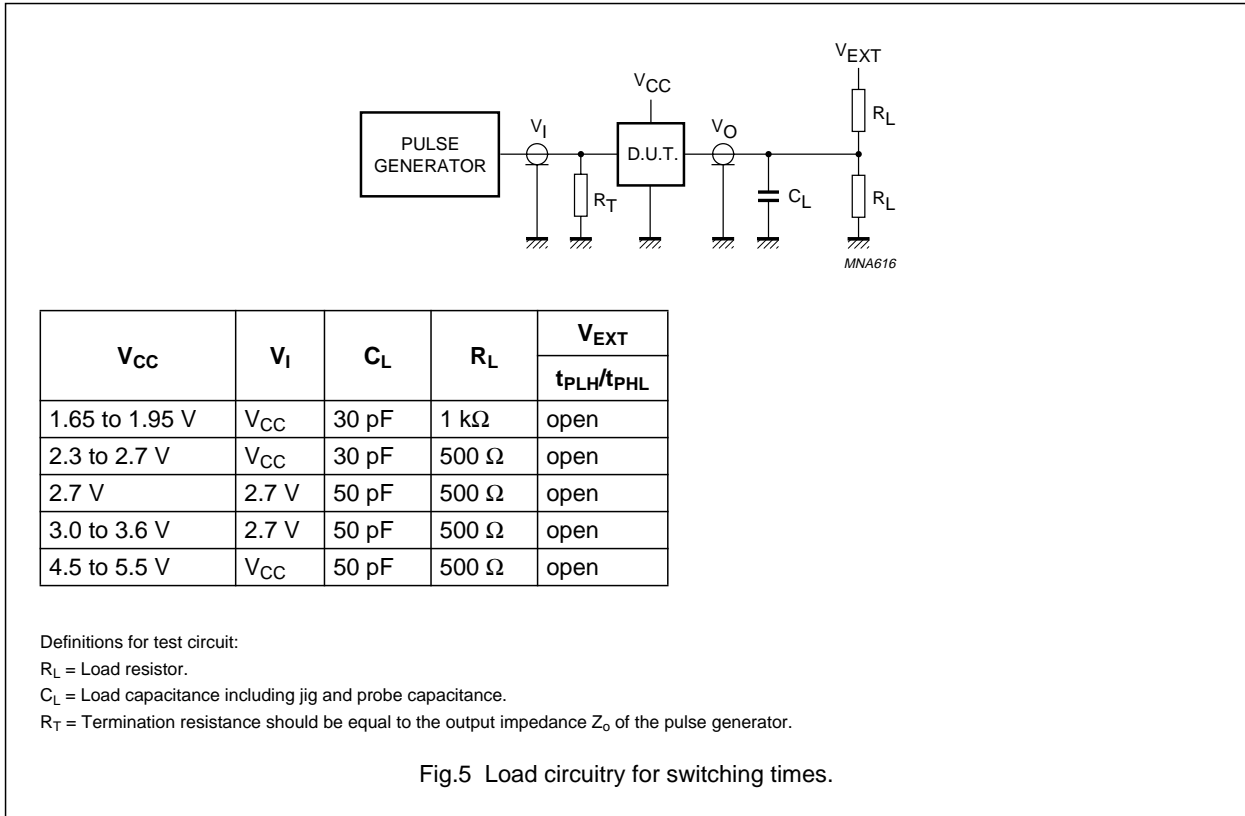
V <sub>CC</sub>	V <sub>M</sub>	INPUT	
		V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>
1.65 to 1.95 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.0 ns
2.3 to 2.7 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.0 ns
2.7 V	1.5 V	2.7 V	≤ 2.5 ns
3.0 to 3.6 V	1.5 V	2.7 V	≤ 2.5 ns
4.5 to 5.5 V	0.5 × V <sub>CC</sub>	V <sub>CC</sub>	≤ 2.5 ns

V<sub>OL</sub> and V<sub>OH</sub> are typical output voltage drop that occur with the output load.

Fig.4 The input X1 to output Y propagation delay.

X-tal driver

74LVC1GX04



# X-tal driver

# 74LVC1GX04

## APPLICATION INFORMATION

Crystal controlled oscillator circuits are widely used in clock pulse generators because of their excellent frequency stability and wide operating frequency range. The use of the 74LVC1GX04 provides the additional advantages of low power dissipation, stable operation over a wide range of frequency and temperature and a very small footprint. This application information describes crystal characteristics, design and testing of crystal oscillator circuits based on the 74LVC1GX04.

### Crystal Characteristics

Figure 8 is the equivalent circuit of a quartz crystal.

The reactive and resistive component of the impedance of the crystal alone and the crystal with a series and a parallel capacitance is shown in Figure 9.

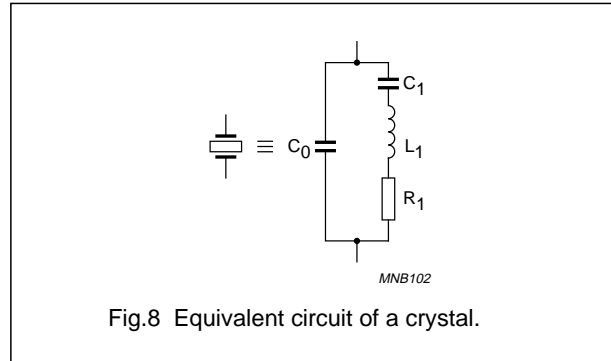


Fig.8 Equivalent circuit of a crystal.

Figure 9 also shows that with a specified load capacitance ( $C_L$ ), the load resonance frequency ( $f_L$ ) is the same for a circuit with either a series (b) or parallel (c) capacitance.  $C_L$  is specified by crystal manufacturers and is used in determining the value of the external components of the oscillator.

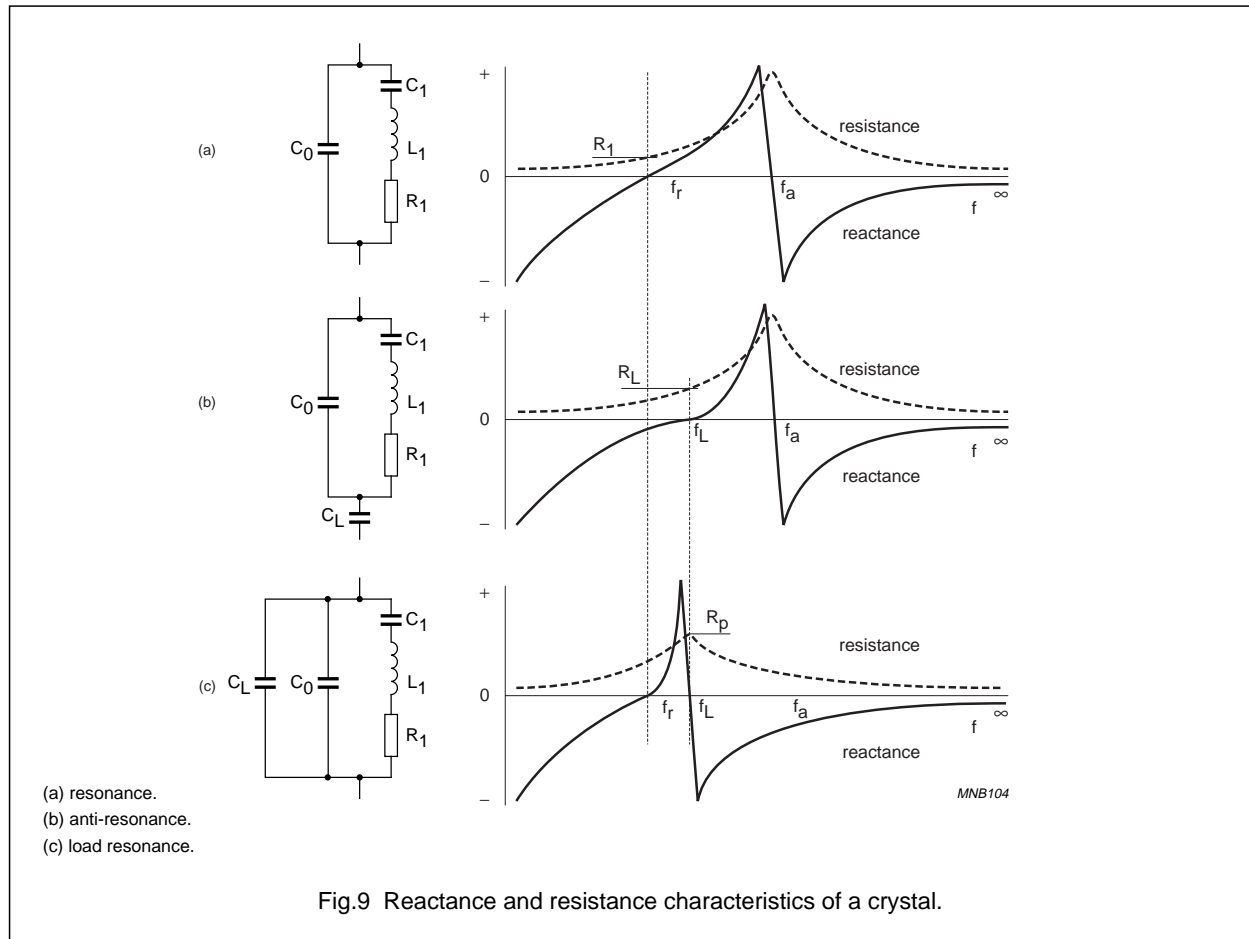


Fig.9 Reactance and resistance characteristics of a crystal.

## X-tal driver

## 74LVC1GX04

## Design

Figure 10 shows the recommended way to connect a crystal to the 74LVC1GX04. This circuit is basically a Pierce oscillator circuit in which the crystal is operating at its fundamental frequency and is tuned by the parallel load capacitance of  $C_1$  and  $C_2$ .  $C_1$  and  $C_2$  are in series with the crystal. They should be approximately equal.  $R_1$  is the drive-limiting resistor and is set to approximately the same value as the reactance of  $C_1$  at the crystal frequency ( $R_1 = X_{C_1}$ ). This will result in an input to the crystal of 50% of the rail-to-rail output of X2. This keeps the drive level into the crystal within drive specifications (the designer should verify this). Overdriving the crystal can cause damage.

The resistor  $R_f$  provides negative feedback and sets a bias point of the inverter near mid-supply, operating the 74LVC1GU04 in the high gain linear region. The value of  $R_f$  is not critical, typically it is set at 1 M $\Omega$ .

To calculate the values of  $C_1$  and  $C_2$ , the designer can use

$$\text{the formula: } C_L = \frac{C_1 \times C_2}{C_1 + C_2} + C_s$$

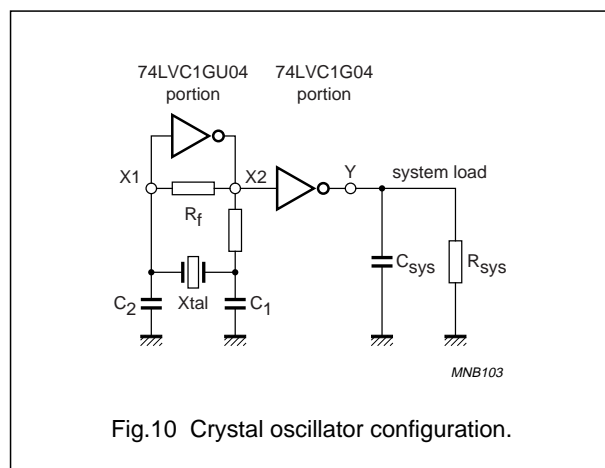
$C_L$  is the load capacitance as specified by the crystal manufacturer,  $C_s$  is the stray capacitance of the circuit (for the LVC1GX04 this is equal to an input capacitance of 5 pf).

## Testing

After the calculations are performed for a particular crystal, the oscillator circuit should be tested. The following simple checks will verify the prototype design of a crystal controlled oscillator circuit. Perform them after laying out the board:

- Test the oscillator over worst-case conditions (lowest supply voltage, worst-case crystal and highest operating temperature). Adding series and parallel resistors can simulate a worse case crystal.
- Insure that the circuit does not oscillate without the crystal.
- Check the frequency stability over a supply range greater than that which is likely to occur during normal operation.
- Check that the start up time is within system requirements.

As the 74LVC1GX04 isolates the system loading, once the design is optimized, the single layout may work in multiple applications for any given crystal.



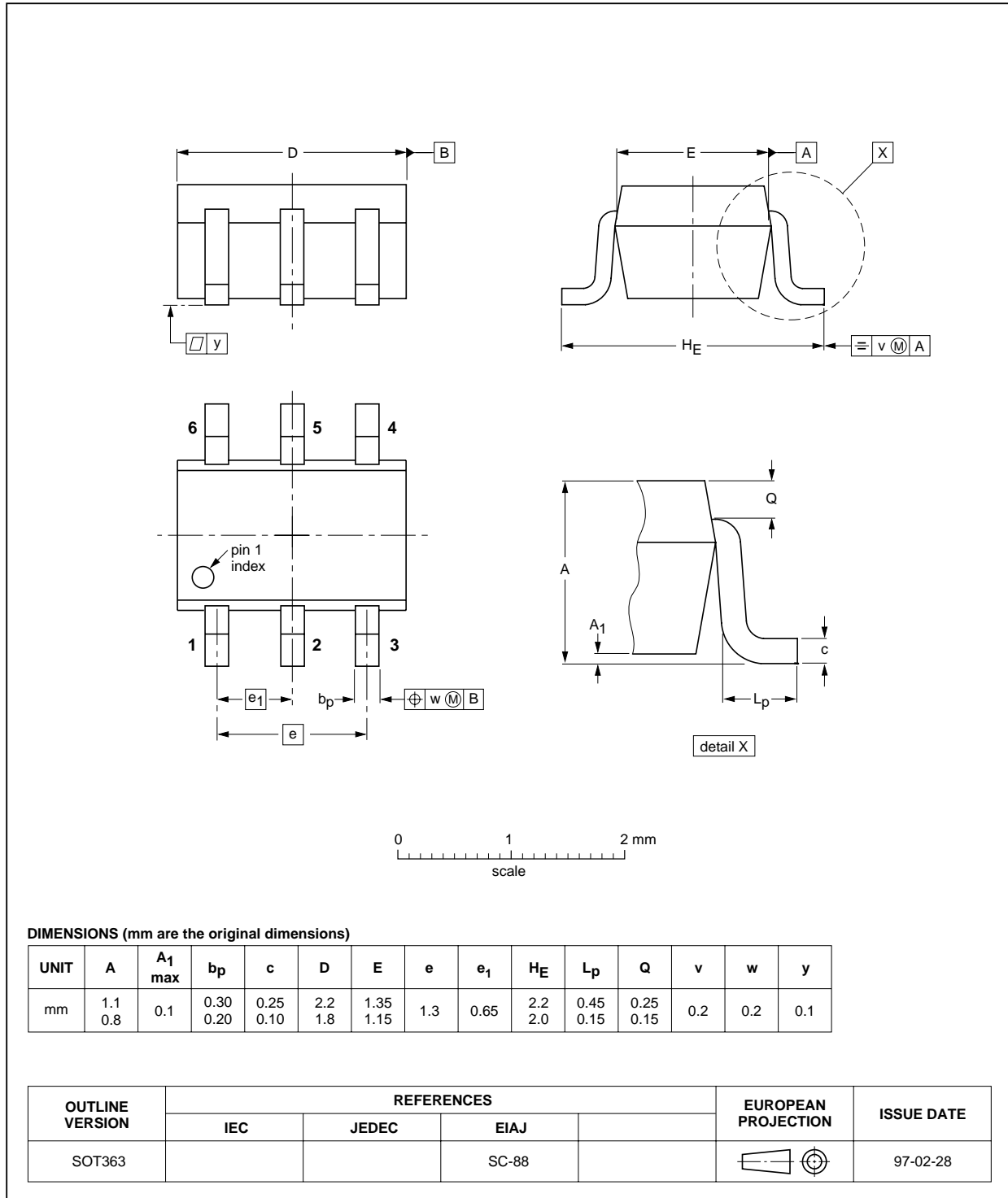
X-tal driver

74LVC1GX04

PACKAGE OUTLINES

Plastic surface mounted package; 6 leads

SOT363

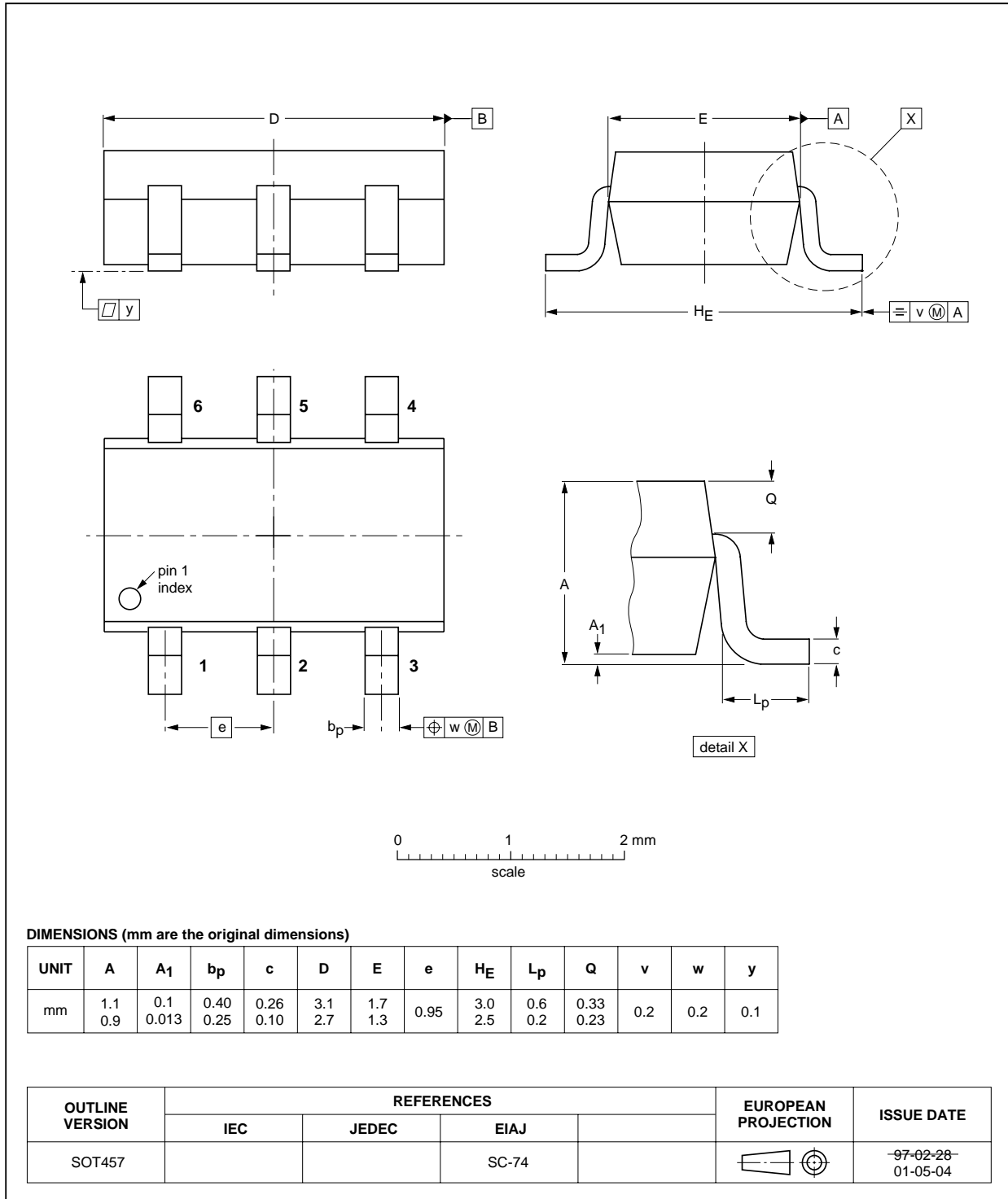


X-tal driver

74LVC1GX04

Plastic surface mounted package; 6 leads

SOT457



## X-tal driver

## 74LVC1GX04

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
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These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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